

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: Jin-Hyuk LEE, et al.

Serial No.: 10/690,782 Examiner: Graybill, David E.

Filed: October 21, 2003 Group Art Unit: 2822

Confirmation No.: 5611

For: METHOD FOR MANUFACTURING A WAFER LEVEL CHIP SCALE  
PACKAGE

Date: September 5, 2006

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT**

Responsive to the Office Action, Paper No. 20060608, dated June 14, 2006, please  
amend the application as follows.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2  
of this paper.

**Remarks/Arguments** begin on page 7 of this paper.